

COVALENT

Covalent Materials Corporation
Nissei Bldg., 6-3, Osaki 1-chome, Shinagawa-ku,
Tokyo 141-0032, Japan

This English translation is provided for the information purpose only. If any discrepancy arises between this translation and the Japanese original, the Japanese original shall prevail

[Translation]

August 10, 2012

To Bondholders:

Covalent Materials Corporation

Notice of Briefing Session for Bondholders of the 1st Series Unsecured Bonds

Covalent Materials Corporation (the "Company") is to hold a briefing session for bondholders of the 1st Series Unsecured Bonds of the Company, as set forth in the press release "Re: Holding of Bondholders Meeting concerning Amendment to the Terms and Conditions (Extension of Maturity Date, etc.) of the 1st Series Unsecured Bond", dated July 30, 2012 (the "July 30 Release"). You are cordially invited to attend.

For details of the amendments to the terms and conditions of the Bonds and the bondholders meeting, please refer to the July 30 Release (note that the briefing session is being held for the purpose of providing information to all bondholders only, and is different from the bondholders meeting that is to be held on September 12).

* * *

1. Date and time: August 29, 2012 (Wednesday), 2:00 pm (reception to begin at 1:30 pm)
2. Location: Convention Hall AP Hamamatsucho, D+E+F Rooms
Shiba Park Building B-kan B1F, Shiba-koen 2-4-1, Minato-ku, Tokyo
※ The explanation by the Company is to be interpreted simultaneously in Japanese and English

Bondholders intending to attend the briefing session are kindly requested to provide, by email or facsimile, their (1) trade name, headquarters location, name of representative and name(s) of session attendee(s) (for corporations) or name and address (for individuals), (2) contact information (person in charge, address, telephone number, facsimile number and email address) and (3) information on the amount of bonds held. All attendees are also kindly requested to bring identification at the briefing session confirming their name and position.

COVALENT

Covalent Materials Corporation
Nissei Bldg, 6-3, Osaki 1-chome, Shinagawa-ku,
Tokyo 141-0032, Japan

The briefing session is to be held for the purpose of providing information to all bondholders only, and we request your kind understanding that attendance by persons other than bondholders may be refused.

* For inquiries regarding the bondholders meeting, and briefing session for bondholders:

Accounting & Finance, Finance Group,
Covalent Materials Corporation

For English communication, please contact us at below E-mail address.
(E-mail: IR-contact@covalent.co.jp Mobile: +81-70-6526-8230)